

## 1. General description

WG75N65UAW1 uses advanced Fine Trench Field-stop IGBT technology with anti-parallel diode in TO-247 package to provide extremely low  $V_{ce(sat)}$ , and excellent switching performance. This device is ideal for wide range switching frequency converters.



## 2. Features and benefits

- Maximum junction temperature 175 °C
- Positive Temperature efficient for Easy Parallel Operating
- Very soft, fast recovery anti-parallel diode
- Smooth & Optimized switching
- EMI improved design

## 3. Applications

- PFC
- Motor control
- UPS
- Resonant converters
- Mid to high range switching frequency applications

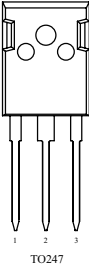
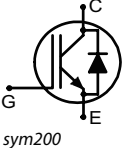
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Notes	Value			Unit	
$V_{CE}$	Collector-emitter voltage, $T_j \geq 25\text{ °C}$		650			V	
$I_C$	DC collector current, limited by $T_{j(max)}$ $T_C = 100\text{ °C}$		75			A	
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
<b>Static characteristics</b>							
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}; I_C = 75\text{ A}; T_j = 25\text{ °C}$		-	1.4	2.0	V

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		
2	C	collector		
3	E	emitter		
mb	C	mounting base; connected to collector		

## 6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WG75N65UAW1	TO247	WG75N65UAW1Q	Tube	30	TO247P	09-Mar-2023

## 7. Marking

Table 4. Marking codes

Type number	Marking codes
WG75N65UAW1	G75N65 UAW1

## 8. Limiting values

Table 5. Limiting values

Symbol	Parameter	Notes	Value	Unit
$V_{CE}$	Collector-emitter voltage, $T_j \geq 25\text{ °C}$		650	V
$I_C$	DC collector current, limited by $T_{j(max)}$ $T_C = 25\text{ °C}$ $T_C = 100\text{ °C}$		150 75	A
$I_{C(puls)}$	Pulsed collector current, $t_p$ limited by $T_{j(max)}$		225	A
-	Turn off safe operating area $V_{CE} \leq 650\text{ V}$ , $T_j \leq 175\text{ °C}$ , $t_p = 1\text{ }\mu\text{s}$		225	A
$I_F$	Diode forward current, limited by $T_{j(max)}$ $T_C = 25\text{ °C}$ $T_C = 100\text{ °C}$		60 30	A
$I_{Fpuls}$	Diode pulsed current, $t_p$ limited by $T_{j(max)}$		90	A
$V_{GE}$	Gate-emitter voltage		$\pm 20$	V
$P_{tot}$	Power dissipation $T_C = 25\text{ °C}$ Power dissipation $T_C = 100\text{ °C}$		600 300	W
$T_{stg}$	Storage temperature		-55 to +150	°C
$T_{jmax}$	Maximum operating junction temperature		175	°C
-	Peak soldering temperature		260	°C
M	Mounting Torque with washer		0.55	Nm

### 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-c)}$	IGBT thermal resistance from junction to case			-	0.25	-	K/W
$R_{th(j-c)}$	Diode thermal resistance from junction to case			-	0.94	-	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient			-	40	-	K/W

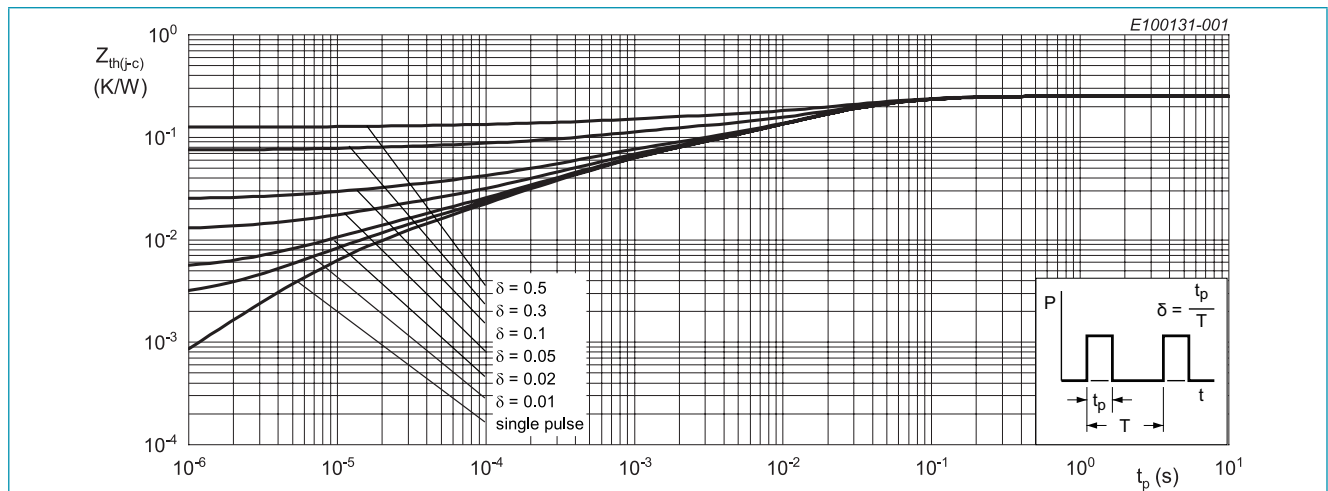


Fig. 1. Transient thermal impedance from junction to case as a function of pulse duration; IGBT

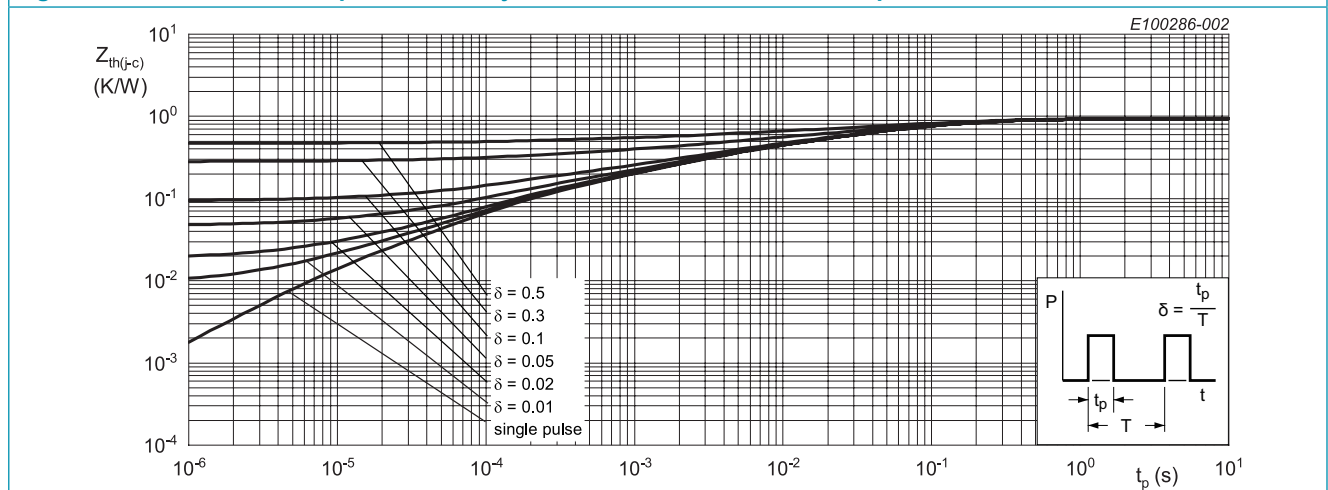


Fig. 2. Transient thermal impedance from junction to case as a function of pulse duration; Diode

## 10. Characteristics

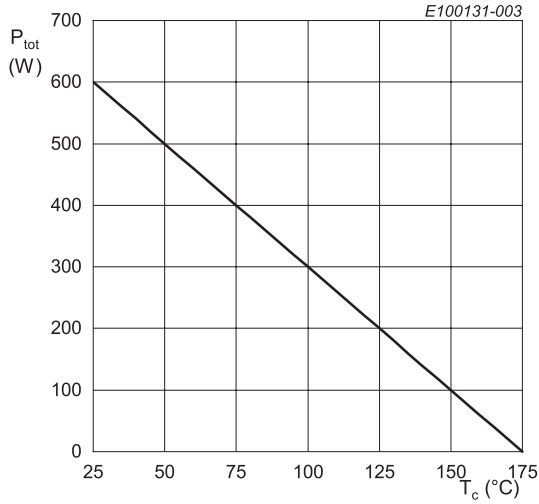
Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
<b>Static characteristics</b>							
$BV_{CES}$	Collector-emitter breakdown voltage	$V_{GE} = 0\text{ V}; I_C = 100\ \mu\text{A}$		650	-	-	V
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}; I_C = 75\text{ A}; T_j = 25\text{ }^\circ\text{C}$		-	1.4	2.0	V
		$V_{GE} = 15\text{ V}; I_C = 75\text{ A}; T_j = 175\text{ }^\circ\text{C}$		-	1.75	-	V
$V_F$	Diode forward voltage	$V_{GE} = 0\text{ V}; I_F = 30\text{ A}; T_j = 25\text{ }^\circ\text{C}$		-	1.9	-	V
		$V_{GE} = 0\text{ V}; I_F = 30\text{ A}; T_j = 175\text{ }^\circ\text{C}$		-	1.5	-	V
$V_{GE(th)}$	Gate-emitter threshold voltage	$I_C = 375\ \mu\text{A}; V_{CE} = V_{GE}$		3.0	4.2	5.5	V
$I_{CES}$	Zero gate voltage collector current	$V_{CE} = 650\text{ V}; V_{GE} = 0\text{ V}; T_j = 25\text{ }^\circ\text{C}$		-	-	100	$\mu\text{A}$
		$V_{CE} = 650\text{ V}; V_{GE} = 0\text{ V}; T_j = 175\text{ }^\circ\text{C}$		-	-	1	mA
$g_{fs}$	Transconductance	$V_{CE} = 20\text{ V}; I_C = 75\text{ A}$		-	68	-	S
<b>Dynamic characteristics</b>							
$C_{ies}$	Input capacitance	$V_{CE} = 30\text{ V}; V_{GE} = 0\text{ V}; f = 1\text{ MHz}; T_j = 25\text{ }^\circ\text{C}$		-	4364	-	pF
$C_{oes}$	Output capacitance			-	170	-	pF
$C_{res}$	Reverse transfer capacitance			-	39	-	pF
$Q_G$	Gate charge	$V_{CC} = 520\text{ V}; I_C = 75\text{ A}; V_{GE} = 15\text{ V}; T_j = 25\text{ }^\circ\text{C}$		-	200	-	nC

## 11. Switching Characteristics

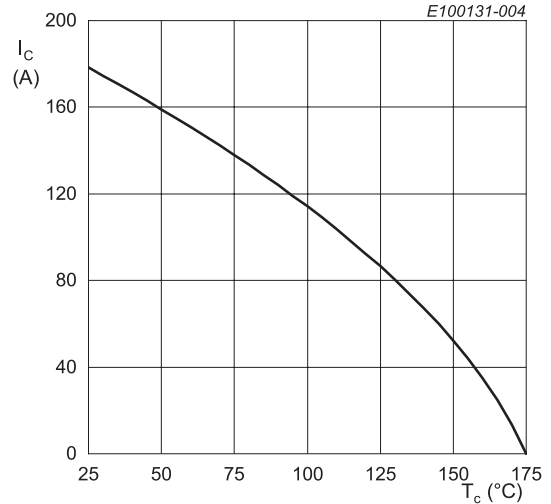
Table 8. Switching Characteristics, Inductive Load

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
<b>IGBT characteristics</b>							
$t_{d(on)}$	Turn-on delay time	$T_J = 25\text{ °C};$ $V_{CC} = 400\text{ V}; I_C = 75\text{ A};$ $V_{GE} = 15\text{ V} / 0\text{ V};$ $R_G = 3.6\ \Omega$		-	40	-	nS
$t_r$	Rise time			-	52	-	nS
$t_{d(off)}$	Turn-off delay time			-	218	-	nS
$t_f$	Fall time			-	56	-	nS
$E_{on}$	Turn-on energy			-	1.9	-	mJ
$E_{off}$	Turn-off energy			-	1.25	-	mJ
$E_{ts}$	Total switching energy			-	3.15	-	mJ
$t_{d(on)}$	Turn-on delay time	$T_J = 175\text{ °C};$ $V_{CC} = 400\text{ V}; I_C = 75\text{ A};$ $V_{GE} = 15\text{ V} / 0\text{ V};$ $R_G = 3.6\ \Omega$		-	39	-	nS
$t_r$	Rise time			-	52	-	nS
$t_{d(off)}$	Turn-off delay time			-	254	-	nS
$t_f$	Fall time			-	58	-	nS
$E_{on}$	Turn-on energy			-	2.65	-	mJ
$E_{off}$	Turn-off energy			-	1.55	-	mJ
$E_{ts}$	Total switching energy			-	4.2	-	mJ
<b>Diode characteristics</b>							
$t_{rr}$	Reverse recovery time	$T_J = 25\text{ °C};$ $V_R = 400\text{ V}; I_F = 30\text{ A};$ $di_F/dt = 500\text{ A/us}$		-	44	-	nS
$Q_r$	Reverse recovery charge			-	221	-	nC
$I_{RM}$	Reverse recovery peak current			-	9	-	A
$t_{rr}$	Reverse recovery time	$T_J = 175\text{ °C};$ $V_R = 400\text{ V}; I_F = 30\text{ A};$ $di_F/dt = 500\text{ A/us}$		-	100	-	nS
$Q_r$	Reverse recovery charge			-	990	-	nC
$I_{RM}$	Reverse recovery peak current			-	17	-	A



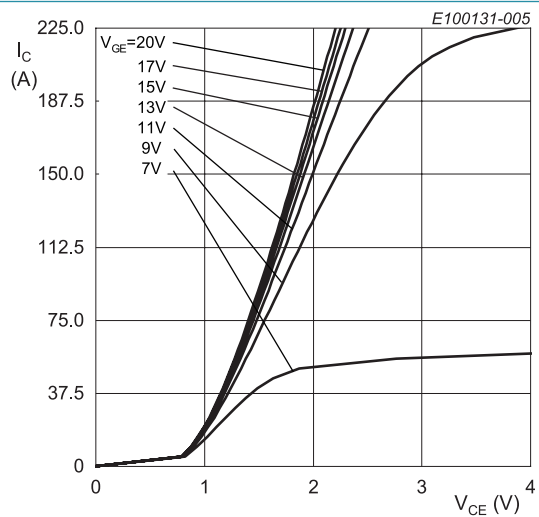
$T_j \leq 175 \text{ }^\circ\text{C}$

**Fig. 3. Power dissipation as a function of case temperature**



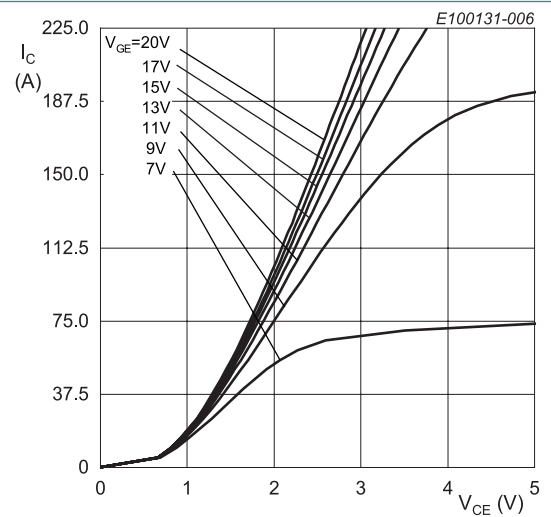
$V_{GE} \geq 15 \text{ V}; T_j \leq 175 \text{ }^\circ\text{C}$

**Fig. 4. Collector current as a function of case temperature**



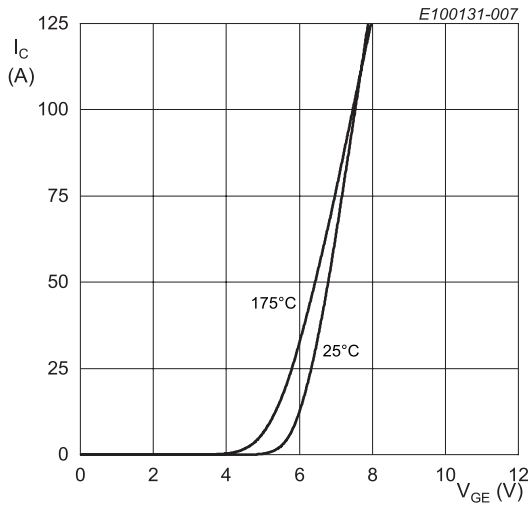
$T_j = 25 \text{ }^\circ\text{C}$

**Fig. 5. Typical output characteristic**



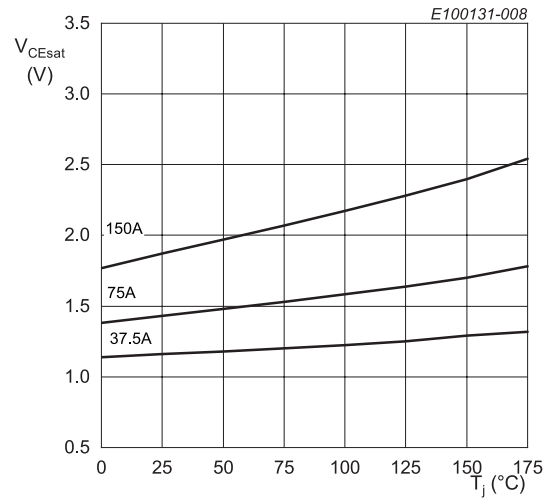
$T_j = 175 \text{ }^\circ\text{C}$

**Fig. 6. Typical output characteristic**



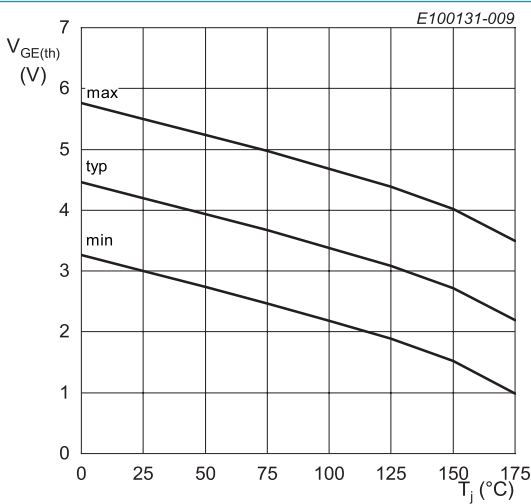
$V_{CE} = 20\text{ V}$

Fig. 7. Typical transfer characteristic



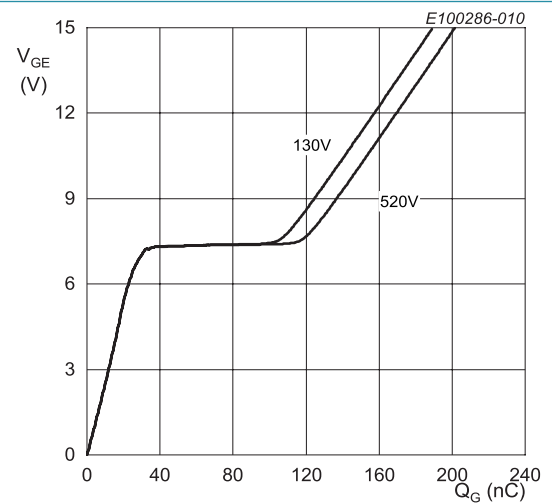
$V_{GE} = 15\text{ V}$

Fig. 8. Typical collector-emitter saturation voltage as a function of junction temperature



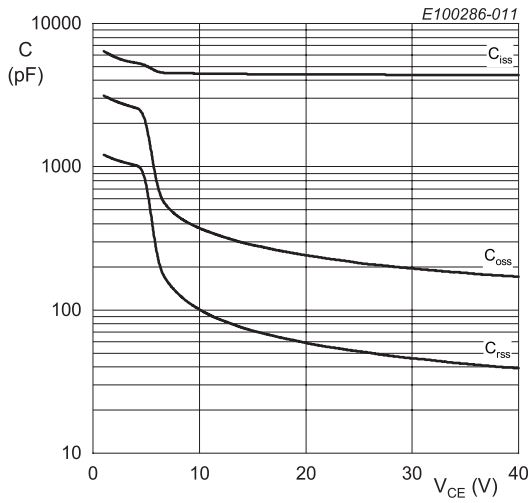
$I_C = 375\ \mu\text{A}$

Fig. 9. Gate-emitter threshold voltage as a function of junction temperature



$I_C = 75\text{ A}$

Fig. 10. Typical gate charge



$V_{GE} = 0\text{ V}; f = 1\text{ MHz}$

Fig. 11. Typical capacitance as a function of collector-emitter voltage

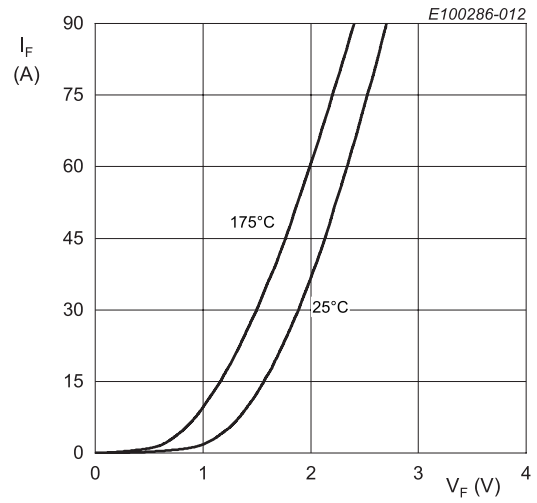
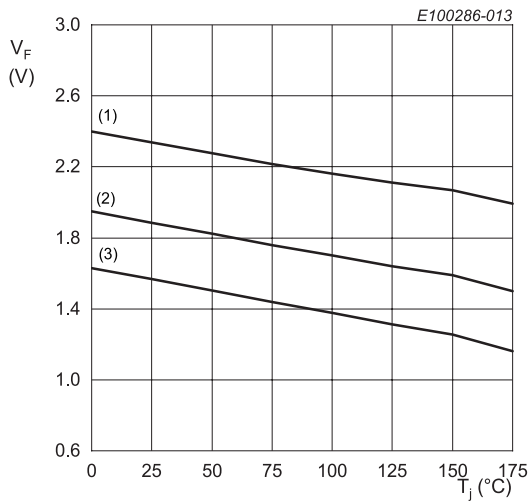
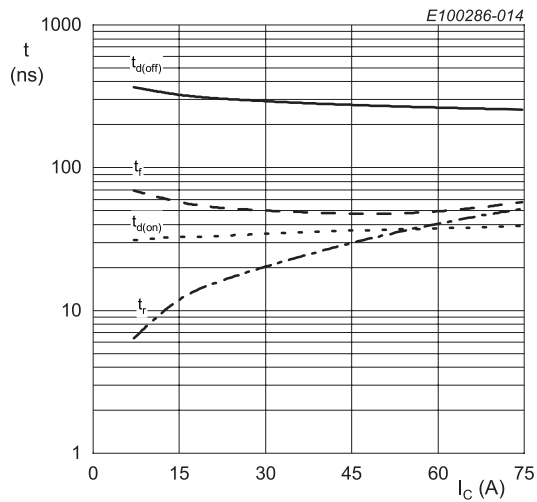


Fig. 12. Typical diode forward current as a function of forward voltage



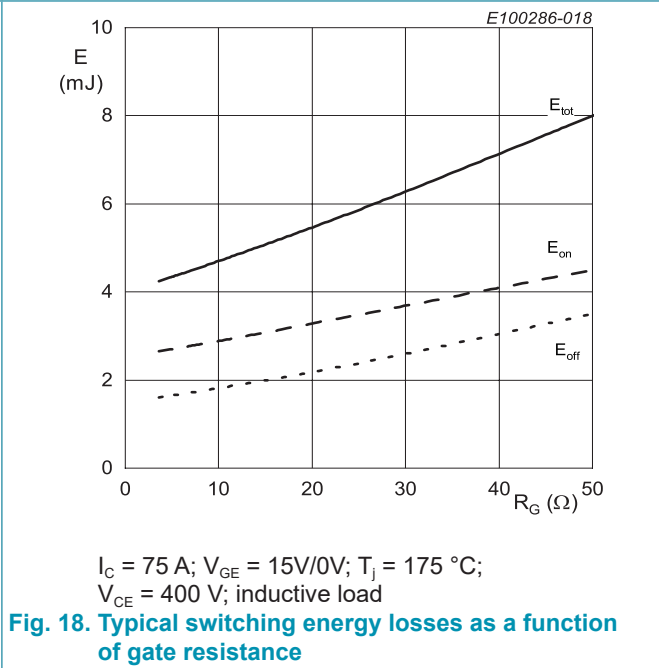
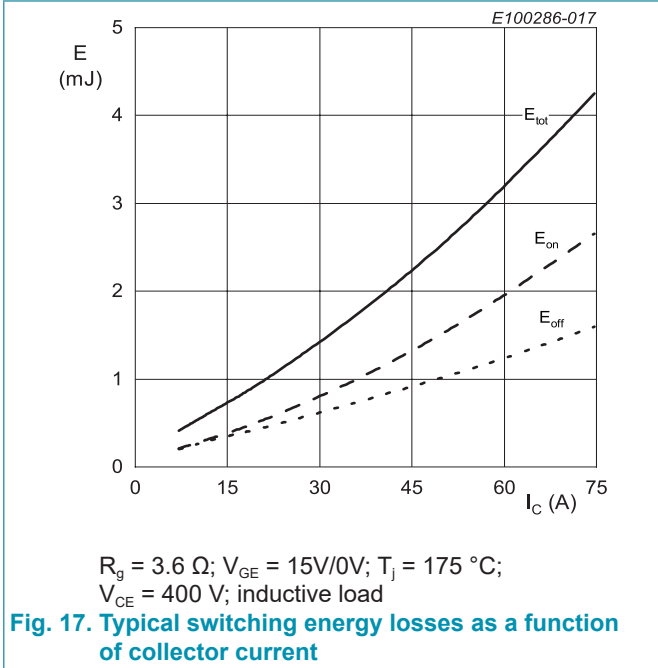
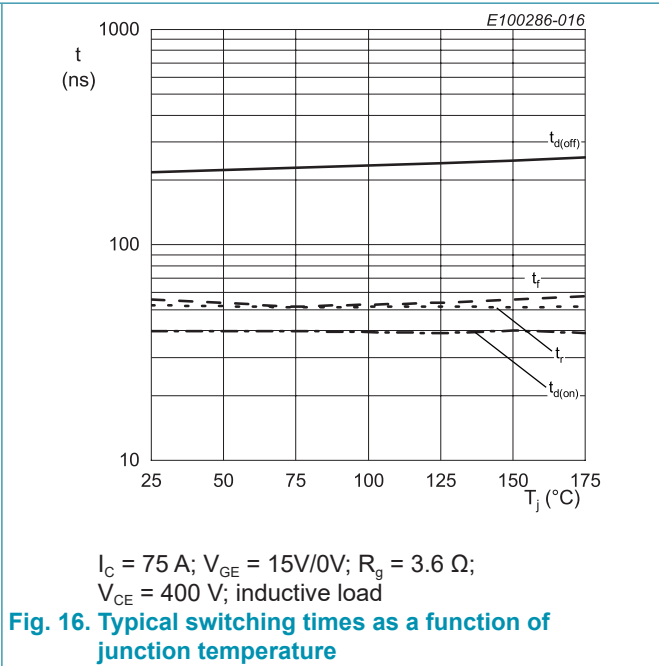
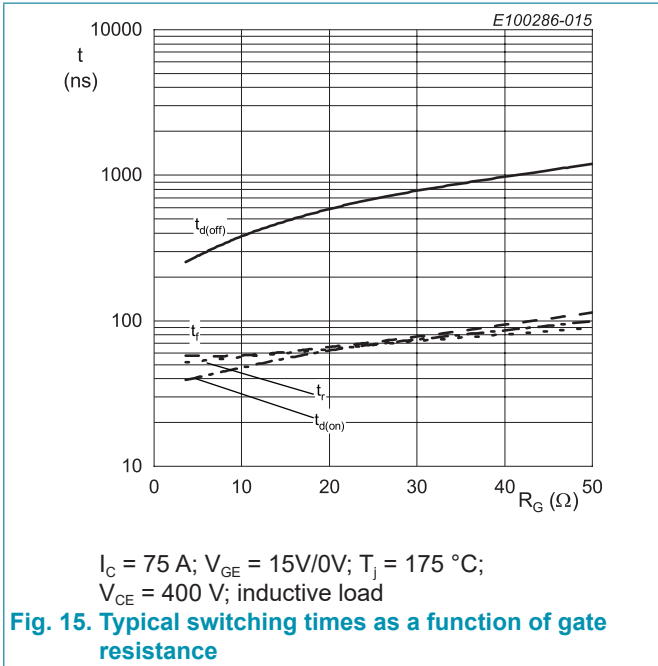
- (1)  $I_F = 60\text{ A}$
- (2)  $I_F = 30\text{ A}$
- (3)  $I_F = 15\text{ A}$

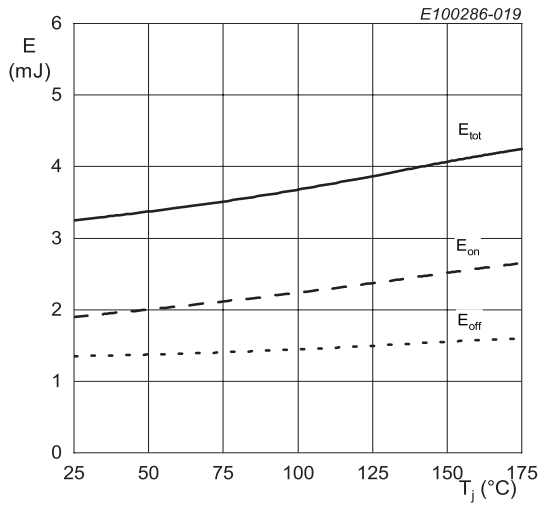
Fig. 13. Typical diode forward voltage as a function of junction temperature



$R_g = 3.6\ \Omega; V_{GE} = 15\text{V}/0\text{V}; T_J = 175\text{ }^\circ\text{C};$   
 $V_{CE} = 400\text{ V};$  inductive load

Fig. 14. Typical switching times as a function of collector current





$I_C = 75 \text{ A}$ ;  $V_{GE} = 15\text{V}/0\text{V}$ ;  $R_g = 3.6 \ \Omega$ ;  
 $V_{CE} = 400 \text{ V}$ ; inductive load

Fig. 19. Typical switching energy losses as a function of junction temperature

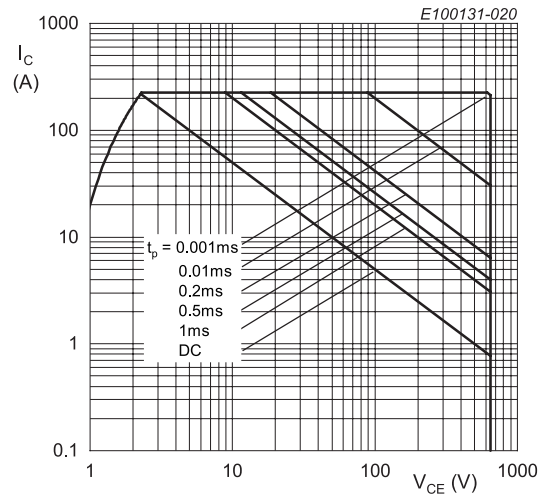


Fig. 20. Forward bias safe operating area

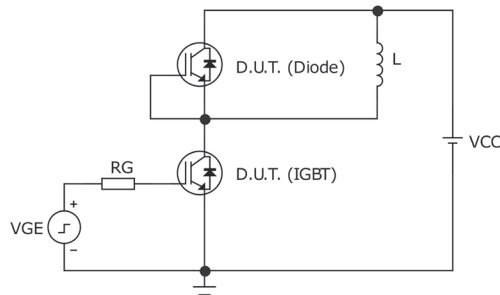


Fig. 21. Test circuit for inductive load switching

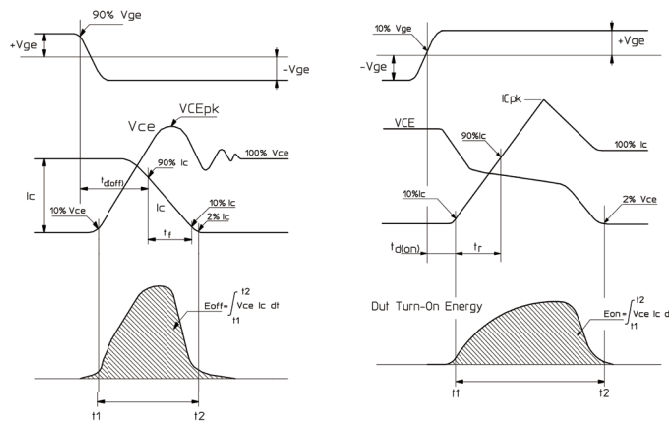
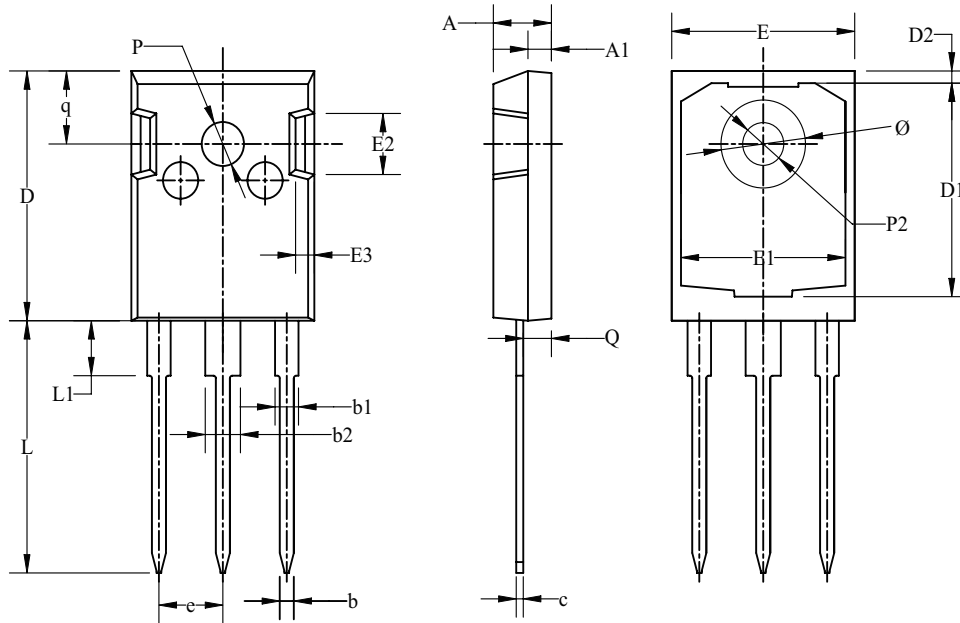


Fig. 22. Definition of switching times and losses

## 12. Package outline

Plastic single-ended through-hole package; headsink mounted; 1 mounting hole; 3 leads TO-247

TO247



Dim	All Dimensions in Millimeters		
	Min	Typ	Max
A	4.70	4.95	5.20
A1	1.90	2.00	2.10
b	1.00	1.20	1.40
b1	1.80	2.00	2.20
b2	2.80	3.00	3.20
c	0.50	0.60	0.70
D	20.30	20.45	20.60
D1	17.28	17.48	17.68
D2	0.80	1.00	1.20
E	15.45	15.60	15.75
E1	13.82	14.02	14.22
E2	4.80	5.00	5.20
E3	1.40	1.60	1.80
e	5.45 BSC		
L	20.40	20.65	20.90
L1	4.25	4.50	4.75
P2	3.40	3.50	3.60
P	3.50	3.60	3.70
Q	2.20	2.40	2.60
q	5.78	5.98	6.18
Ø	7.10	7.19	7.30

## 13. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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Date of release: 05 December 2024

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